



PATENT APPLICATION

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Nobuaki HASHIMOTO

Group Art Unit: 2826

Application No.: 09/856,924

Examiner: Tan N. Tran

Filed: May 30, 2001

Docket No.: 109681

For: SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAME,
CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

AMENDMENT UNDER 37 C.F.R. §1.111

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed June 18, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 1, 3, 7, 10 and 13 as follows:

B' Sub C' 1. (Amended) A semiconductor device comprising:
a substrate including a plurality of holes and a surface over which an interconnecting pattern is formed, part of the interconnecting pattern being superposed over the holes;
a semiconductor chip disposed over another surface of the substrate and including a plurality of electrodes to be positioned over the holes; and
conductive posts provided on the electrodes and within the holes to be electrically connected to the interconnecting pattern.

B2 D1 3. (Amended) The semiconductor device as defined in claim 2,
wherein the resin is an anisotropic conductive material containing conductive particles; and